

Nch 60V 70A Power MOSFET

V <sub>DSS</sub>	60V
R <sub>DS(on)</sub> (Max.)	7.2mΩ
I <sub>D</sub>	±70A
P <sub>D</sub>	96W

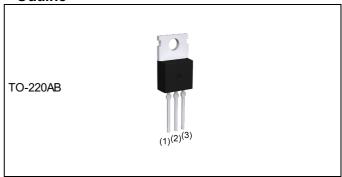
## ● Features

- 1) Low on resistance
- 2) High power small mold package (TO220AB)
- 3) Pb-free plating; RoHS compliant
- 4) 100% Rg and UIS tested
- 5) Halogen free

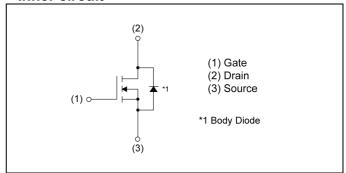
## Application

Switching

## Outline



## •Inner circuit



Packaging specifications

or ackaging specifications						
	Packing	Tube				
T. 120	Quantity (pcs)	1000				
Type	Taping code	C16				
	Marking	RX3L07BGN				

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	60	V
Continuous drain current	I <sub>D</sub> *1	±70	Α
Pulsed drain current	I <sub>DP</sub> *2	±140	Α
Gate - Source voltage	$V_{GSS}$	±20	V
Avalanche current, single pulse	l <sub>AS</sub> *3	37	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	52	mJ
Power dissipation	P <sub>D</sub> *1	96	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperating	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Doromotor	Symbol		Values		Lloit
Parameter		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	1.3	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Llmit
Parameter	Symbol	ol Conditions –		Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	60	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	60	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	10	μА
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		1	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{GS(th)}$ $V_{DS} = V_{GS}$ , $I_D = 50\mu A$		-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$			-5.6	-	mV/°C
Static drain - source	D *4	V <sub>GS</sub> = 10V, I <sub>D</sub> = 70A	-	5.2	7.2	mO.
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 35A	-	7.3	10.9	mΩ
Gate resistance	R <sub>G</sub> f = 1MHz, open drain		-	1.8	1	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 5V, I <sub>D</sub> = 35A	60	-	-	S

<sup>\*1</sup> T<sub>c</sub>=25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  0.05mH, V<sub>DD</sub> = 30V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>i</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Doramatar	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2600	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 30V	-	510	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	130	1	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 30V, V_{GS} = 10V$	1	17	1	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 40A	1	32	1	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 0.75\Omega$	-	71	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	34	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Company of	Conditions			Values		Lloit	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Total gate charge	Qg*4		V <sub>GS</sub> = 10V	-	55	-		
Total gate charge		$\mathcal{Q}_{g}$ .	$Q_g$	V <sub>DD</sub> ≃ 30V		-	27	-
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 40A	V <sub>GS</sub> = 4.5V	-	11	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *4			-	9.8	-		

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Unit		
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	1	-	70	Α
Pulse forward current	I <sub>SP</sub> *2	1 <sub>a</sub> - 25 C	-	-	140	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = 70A$	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = 50A, V <sub>GS</sub> =0V	-	42	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/μs	-	53	1	nC

Fig.1 Power Dissipation Derating Curve

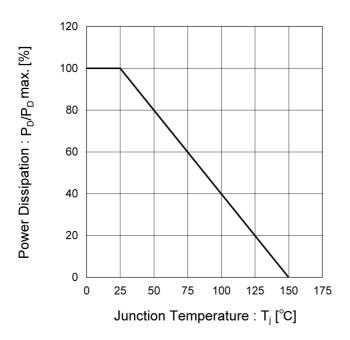
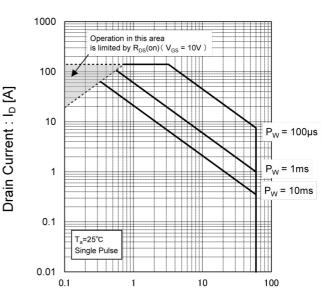


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

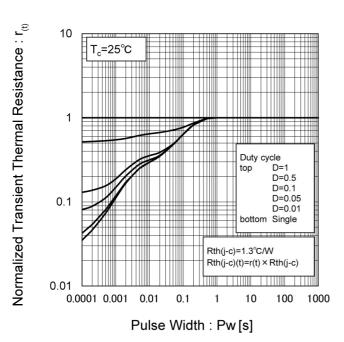


Fig.4 Single Pulse Maximum Power Dissipation

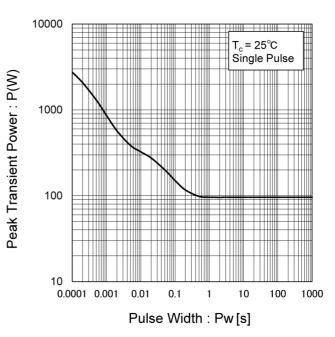
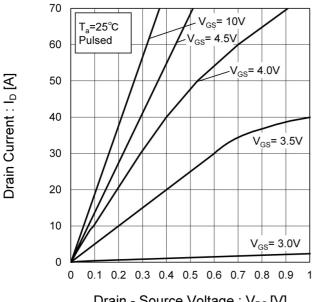
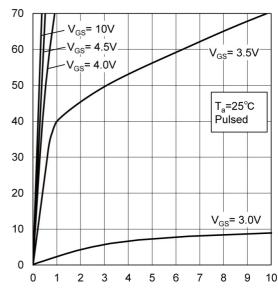


Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs. **Junction Temperature** 

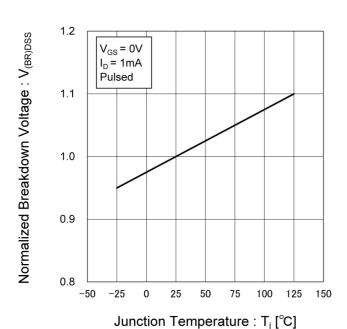


Fig.8 Typical Transfer Characteristics

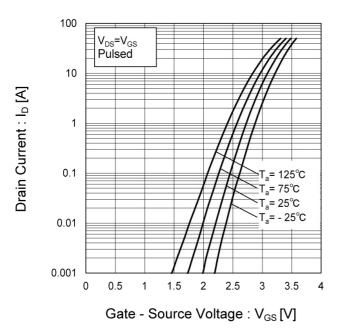


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

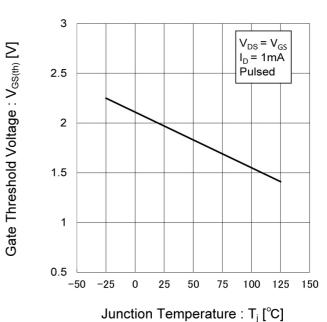


Fig.10 Forward Transfer Admittance vs.
Drain Current

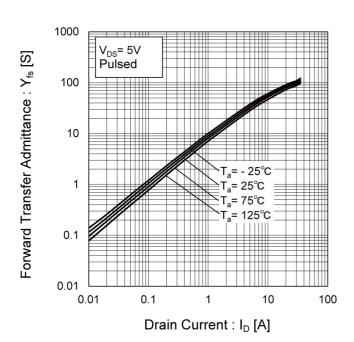


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

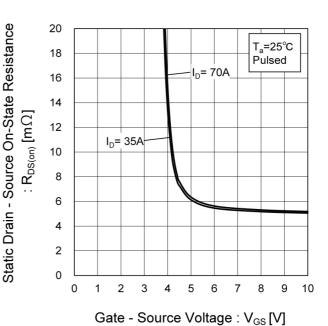


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

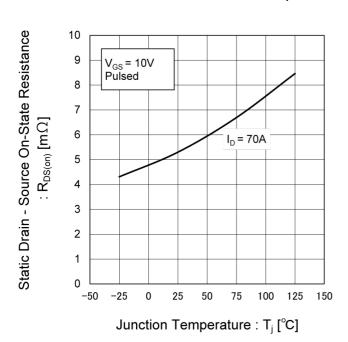


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

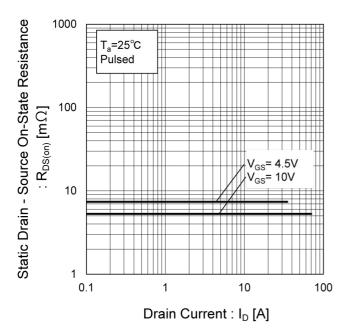


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

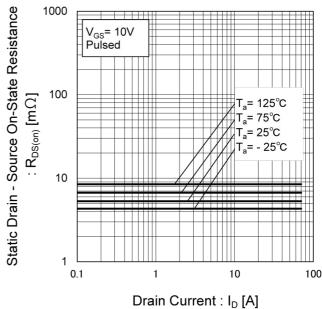


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

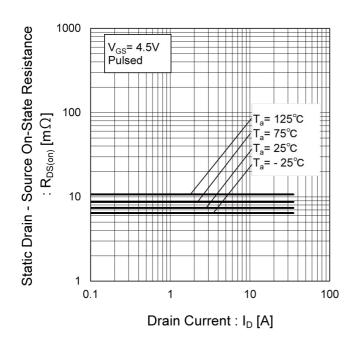


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

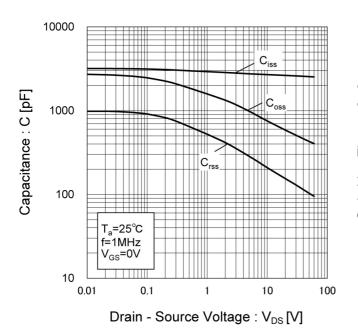


Fig.18 Switching Characteristics

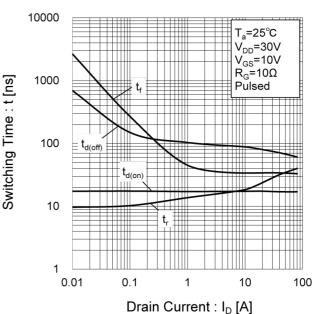


Fig.19 Typical Gate Charge

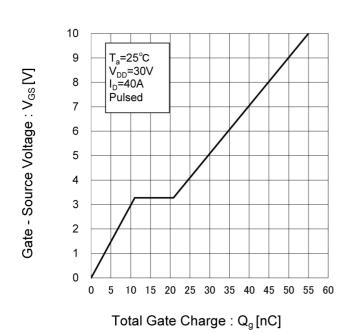
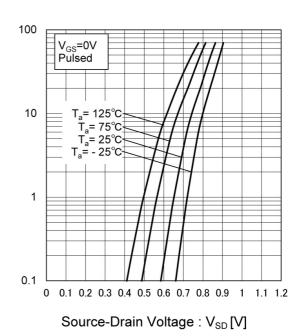


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

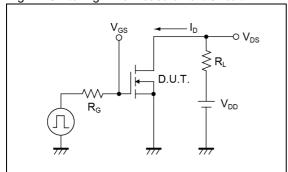


Fig.2-1 Gate Charge Measurement Circuit

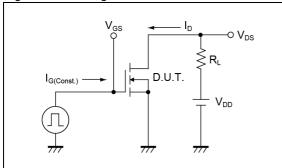


Fig.3-1 Avalanche Measurement Circuit

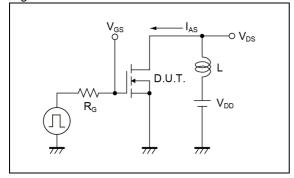


Fig.1-2 Switching Waveforms

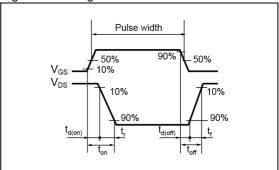


Fig.2-2 Gate Charge Waveform

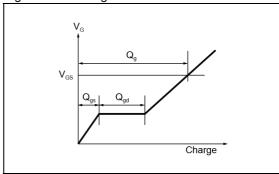
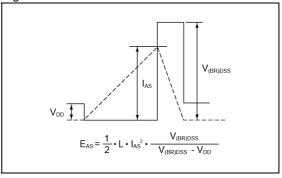
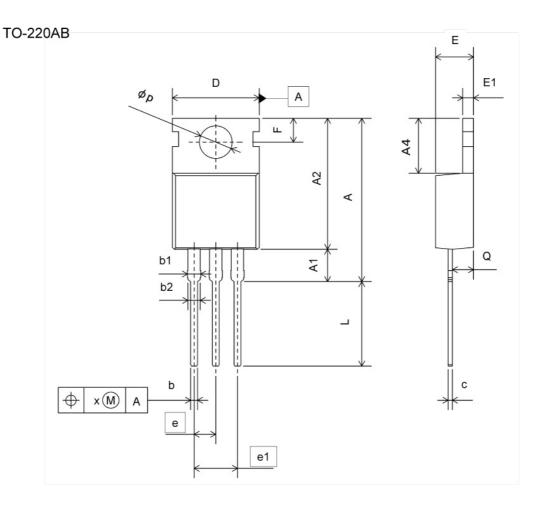


Fig.3-2 Avalanche Waveform



## Dimensions



DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
Α	18.30	20.00	0.720	0.787
A1	3.60	4.00	0.142	0.157
A2	14.70	16.00	0.579	0.630
A4	6.30	6.60	0.248	0.260
b	0.65	0.95	0.026	0.037
b1	1.20	1.75	0.047	0.069
b2	1.20	1.70	0.047	0.067
С	0.35	0.65	0.014	0.026
D	9.96	10.36	0.392	0.408
E	4.24	4.64	0.167	0.183
E1	1.14	1.40	0.045	0.055
е	2.	2.54		00
e1	5.	08	0.2	200
F	2.60	3.00	0.102	0.118
L	9.47	10.37	0.373	0.408
$\phi$ p	3.69	3.99	0.145	0.157
Q	2.30	2.70	0.091	0.106
Х	-0	0.38	-	0.015

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	CL ACCTI	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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